

Title (en)

DOUGH COMPOSITIONS FOR MAKING HALF-PRODUCTS AND FARINACEOUS SNACKS PRODUCED THEREFROM

Title (de)

TEIGZUSAMMENSETZUNG ZUR HERSTELLUNG VON HALBFERTIGPRODUKTEN UND DARAUS HERGESTELLTE MEHLHALTIGE SNACK-PRODUKTE

Title (fr)

COMPOSITIONS DE PATE DESTINEES A LA FABRICATION DE PRODUITS SEMI-FINIS, ET EN-CAS FARINEUX PRODUITS A PARTIR DE CELLES-CI

Publication

EP 1065944 A1 20010110 (EN)

Application

EP 99916260 A 19990401

Priority

- US 9907169 W 19990401
- US 8042598 P 19980402

Abstract (en)

[origin: WO9951111A1] A farinaceous snack having improved flavor and organoleptical properties is made from an extruded half-product. The half-product is produced from a dough consisting essentially of: (1) a flour blend comprising (a) a starch-based flour component comprising at least about 10 % rice flour; (b) less than about 8 % sugar; (c) at least about 0.5 % salt; (d) leavening comprising sodium bicarbonate; (e) emulsifier comprising monoglyceride; and (2) water. Optionally, starch and/or gluten may be added to the flour component to produce final products having various degrees of crispness. A full-fat, low-fat or fat-free product can be made. Embossing may be used to control expansion, surface greasiness and fat pick-up. The flour is preconditioned and the dough is extruded under low-shear and high-water conditions. The dough composition, which forms sufficient viscosity upon heating and cooling, permits processing the dough at temperatures and work input levels below that which would result in substantial degradation of the starches and/or discoloration and loss of flavor components of the ingredients. A rapid drying method, used to dry the extrudate, improves the manufacturing capabilities without sacrificing the desired product attributes. The extrudates may be dried at a temperature of from about 175 DEG F (79.4 DEG C) to about 200 DEG F (93.3 DEG C) at a relative humidity (R.H.) of at least about 20 % for about 1.0 hour to about 4 hours. The half-products may be packaged immediately after drying and do not require tempering.

IPC 1-7

A23L 1/164

IPC 8 full level

A23L 1/164 (2006.01); **A23L 7/10** (2016.01); **A23L 19/18** (2016.01)

CPC (source: EP)

A23L 7/13 (2016.07)

Citation (search report)

See references of WO 9951111A1

Cited by

CN102960630A; US11297842B2; USD864516S

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU NL PT SE

DOCDB simple family (publication)

WO 9951111 A1 19991014; AU 3461599 A 19991025; BR 9909297 A 20001205; CA 2326590 A1 19991014; CN 1295444 A 20010516; EP 1065944 A1 20010110; JP 2002510476 A 20020409

DOCDB simple family (application)

US 9907169 W 19990401; AU 3461599 A 19990401; BR 9909297 A 19990401; CA 2326590 A 19990401; CN 99804622 A 19990401; EP 99916260 A 19990401; JP 2000541891 A 19990401